



# Product Change Notification



Product Group: Vishay Dale/January 6, 2021/PCN-DI-00502-2021 Rev 0

## Bulk Packaging Obsolescence on series IHLP, IHLG, IHLM, IHLE, IHLW, IHLD, and IHCL

**DESCRIPTION OF CHANGE:** The bulk package codes (EB / PJ) are becoming obsolete on the Vishay IHLP, IHLG, IHLM, IHLE, IHLW, IHLD, and IHCL series. These inductors are still available by using the tape and reel package code (ER / RZ) but are subject to a 1 reel MOQ (minimum order quantity).

**CLASSIFICATION OF CHANGE:** Product Obsolescence

**REASON FOR CHANGE:** Streamline the IHLP production line

**EXPECTED INFLUENCE ON QUALITY/RELIABILITY/PERFORMANCE:** N/A

**PRODUCT CATEGORY:** Inductors

**PART NUMBERS/SERIES/FAMILIES AFFECTED:** See separate part number list

**VISHAY BRAND(s):** Vishay Dale

**TIME SCHEDULE:**

Start Shipment Date: N/A

Last Time Buy Date: 3/6/2021

Last Time Shipment Date: 6/6/2021

**SAMPLE AVAILABILITY:** N/A

**PRODUCT IDENTIFICATION:** N/A

**QUALIFICATION DATA:** N/A

**This PCN is considered approved, without further notification, unless we receive specific customer concerns or as specified by contract.**

**ISSUED BY:** Doug Lillie, Sr. Product Marketing Manager

**For further information, please contact your regional Vishay office.**

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